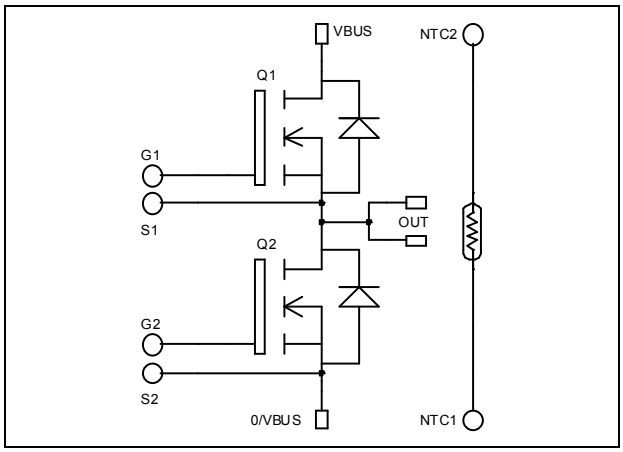
APTM50AM38FTG

Phase leg MOSFET Power Module

V_{DSS} = 500V
R_{DSon} = 38mΩ typ @ Tj = 25°C
I_D = 90A @ Tc = 25°C

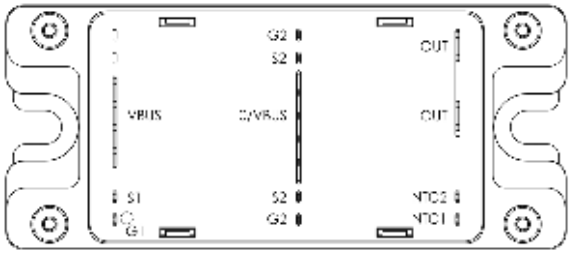


Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7® FREDFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Fast intrinsic reverse diode
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration



Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		500	V
I_D	Continuous Drain Current	T_c = 25°C	90	A
		T_c = 80°C	67	
I_{DM}	Pulsed Drain current		360	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		45	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	694	W
I_{AR}	Avalanche current (repetitive and non repetitive)		46	A
E_{AR}	Repetitive Avalanche Energy		50	mJ
E_{AS}	Single Pulse Avalanche Energy		2500	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V, V_{DS} = 500V	T_j = 25°C			200	µA
		V_{GS} = 0V, V_{DS} = 400V	T_j = 125°C			1000	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 45A			38	45	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 5mA		3		5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V, V_{DS} = 0V				±150	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		11.2		nF
C_{oss}	Output Capacitance			2.4		
C_{rss}	Reverse Transfer Capacitance			0.18		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 250V I_D = 90A		246		nC
Q_{gs}	Gate – Source Charge			66		
Q_{gd}	Gate – Drain Charge			130		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 333V I_D = 90A R_G = 2Ω		18		ns
T_r	Rise Time			35		
$T_{d(off)}$	Turn-off Delay Time			87		
T_f	Fall Time			77		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 25°C** V_{GS} = 15V, V_{Bus} = 333V I_D = 90A, R_G = 2Ω		1510		µJ
E_{off}	Turn-off Switching Energy			1452		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 333V I_D = 90A, R_G = 2Ω		2482		µJ
E_{off}	Turn-off Switching Energy			1692		

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_S	Continuous Source current (Body diode)		Tc = 25°C			90	A
			Tc = 80°C			67	
V_{SD}	Diode Forward Voltage	V_{GS} = 0V, I_S = - 90A				1.3	V
dv/dt	Peak Diode Recovery ❶					15	V/ns
t_{rr}	Reverse Recovery Time	I_S = - 90A V_R = 333V di_S/dt = 200A/µs	T_j = 25°C		233		ns
			T_j = 125°C		499		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		3.8		µC
			T_j = 125°C		11.4		

❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.
I_S ≤ - 90A di/dt ≤ 700A/µs V_R ≤ V_{DSS} T_j ≤ 150°C

Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance					0.18	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_J	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To Heatsink	M5	2.5		4.7	N.m
Wt	Package Weight					160	g

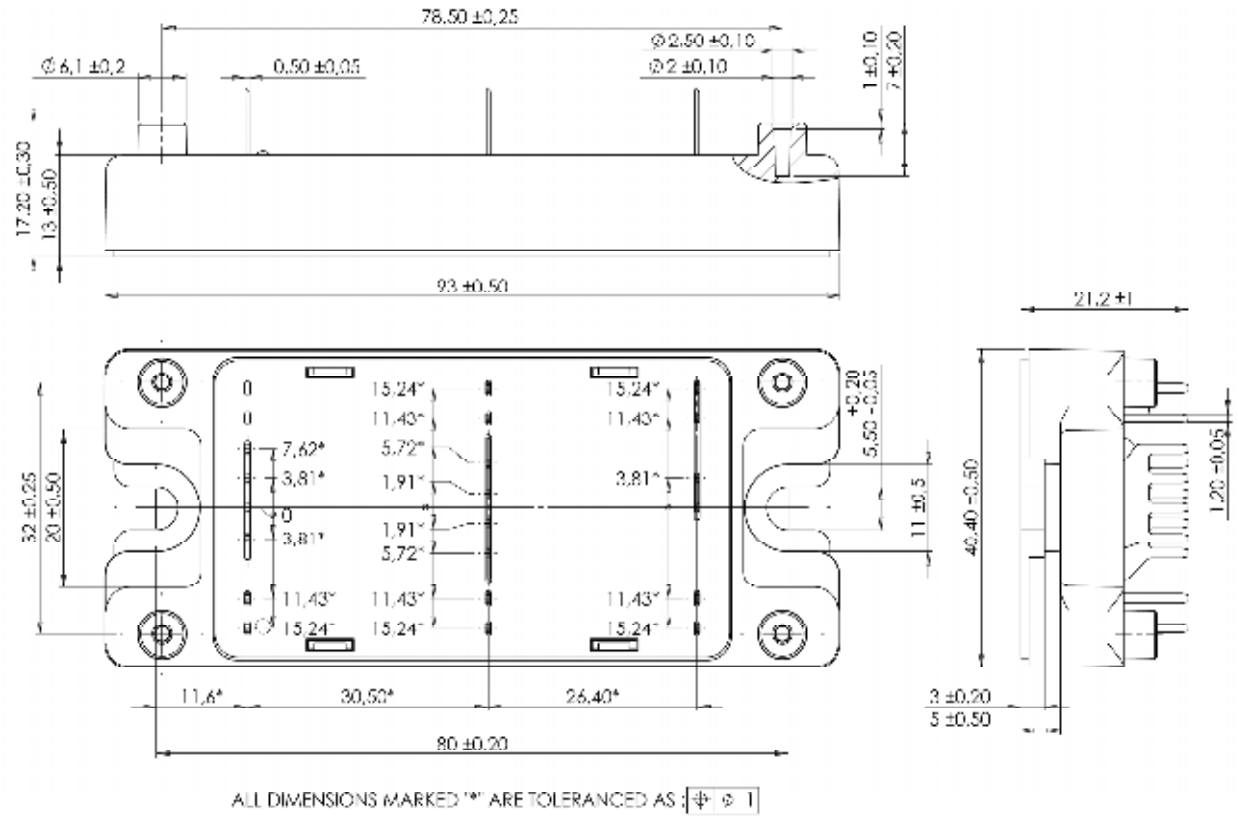
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C		50		kΩ
$B_{25/85}$	T_{25} = 298.15 K		3952		K

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

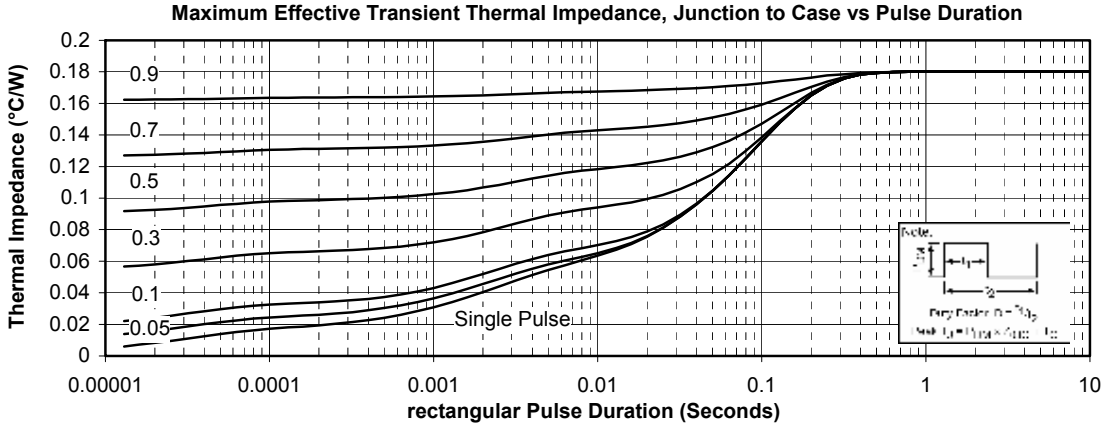
T: Thermistor temperature
R_T: Thermistor value at T

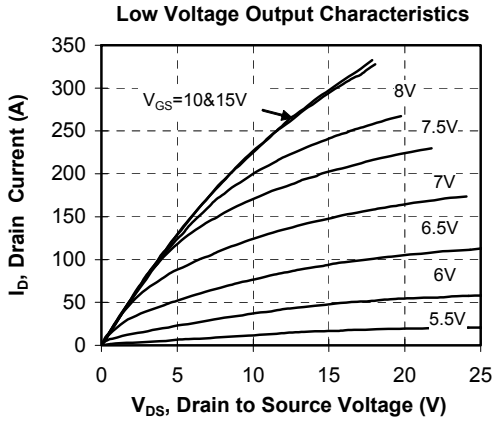
SP4 Package outline (dimensions in mm)

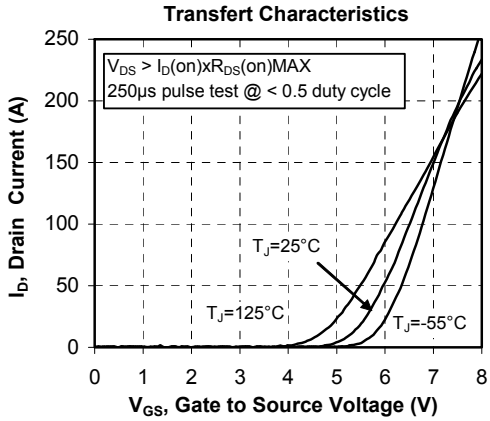


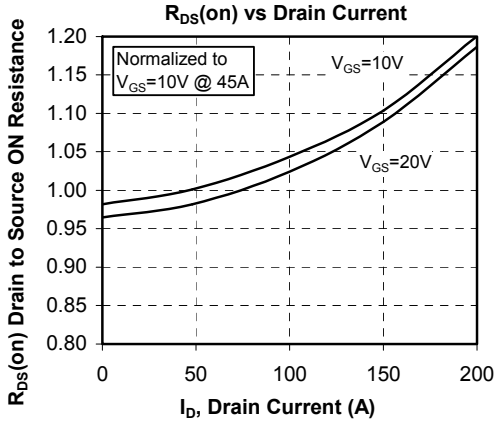
See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

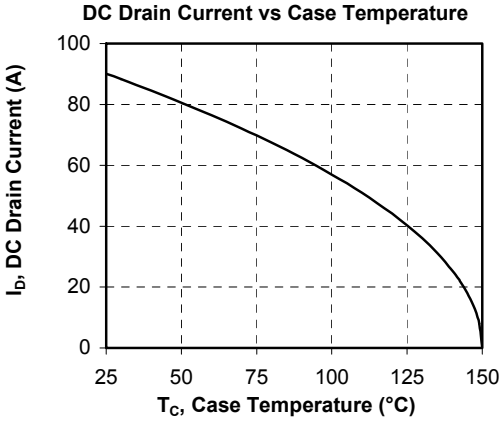
Typical Performance Curve

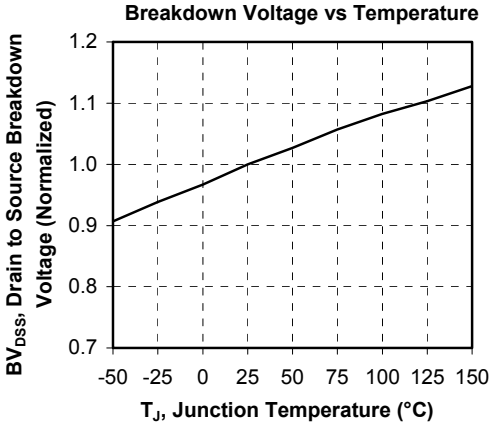


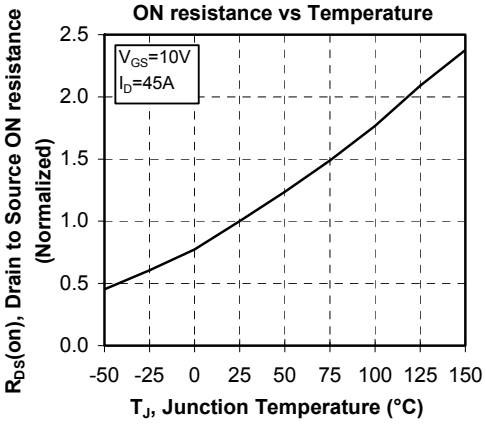


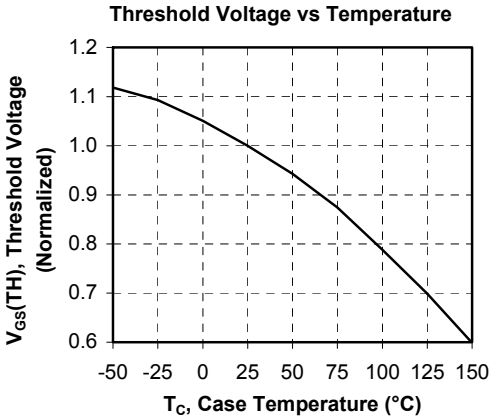


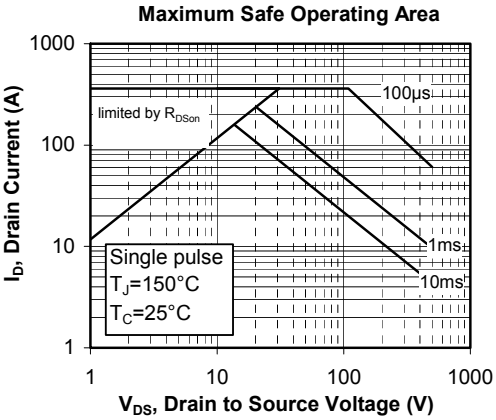


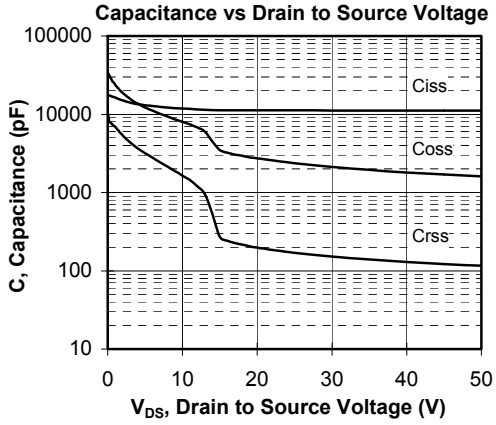


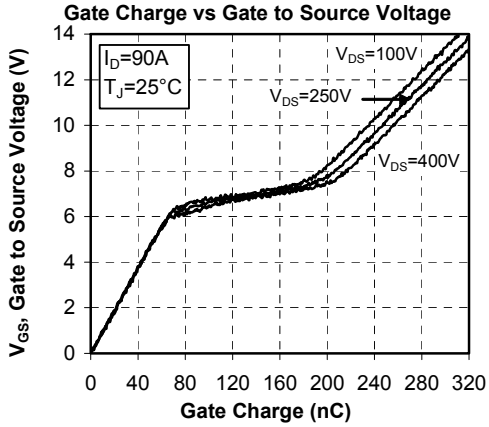

Breakdown Voltage vs Temperature
BVDSS, Drain to Source Breakdown Voltage (Normalized)
1.2
1.1
1.0
0.9
0.8
0.7
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)

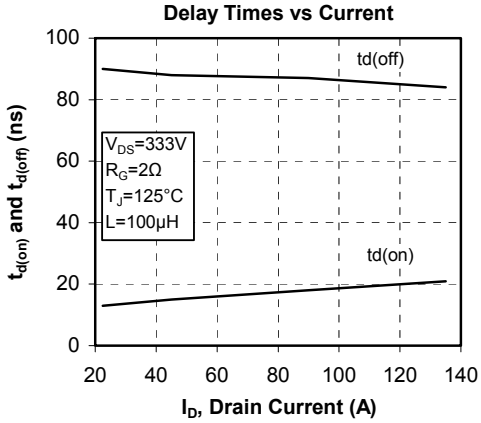

ON resistance vs Temperature
VGS=10V
ID=45A
RDS(on), Drain to Source ON resistance (Normalized)
2.5
2.0
1.5
1.0
0.5
0.0
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)

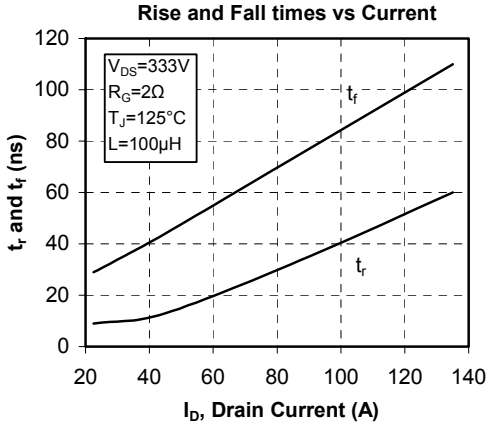

Threshold Voltage vs Temperature
VGS(TH), Threshold Voltage (Normalized)
1.2
1.1
1.0
0.9
0.8
0.7
0.6
-50 -25 0 25 50 75 100 125 150
TC, Case Temperature (°C)

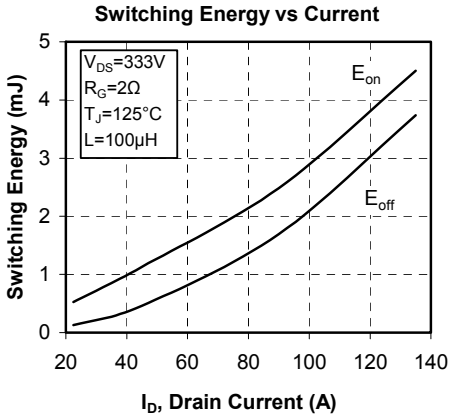

Maximum Safe Operating Area
ID, Drain Current (A)
1000
100
10
1
limited by RDSon
100µs
1ms
10ms
Single pulse
TJ=150°C
TC=25°C
1 10 100 1000
VDS, Drain to Source Voltage (V)

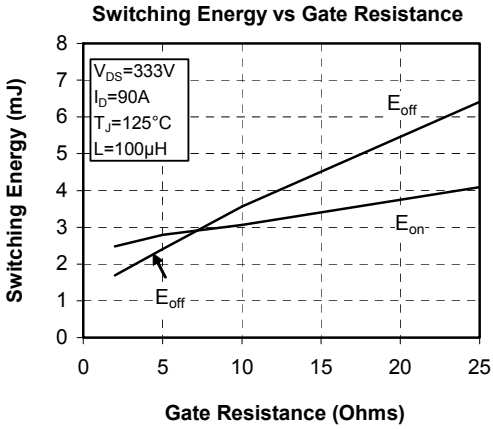

Capacitance vs Drain to Source Voltage
C, Capacitance (pF)
100000
10000
1000
100
10
Ciss
Coss
Crss
0 10 20 30 40 50
VDS, Drain to Source Voltage (V)

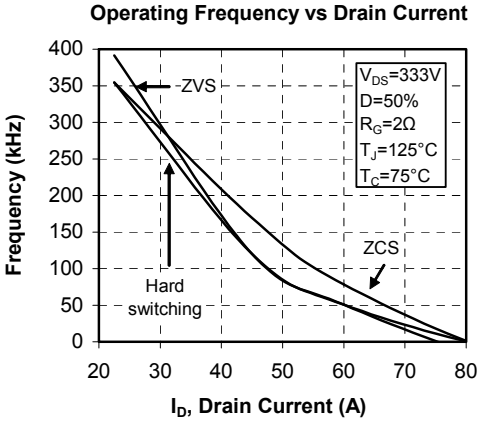

Gate Charge vs Gate to Source Voltage
ID=90A
TJ=25°C
VDS=100V
VDS=250V
VDS=400V
VGS, Gate to Source Voltage (V)
14
12
10
8
6
4
2
0
0 40 80 120 160 200 240 280 320
Gate Charge (nC)

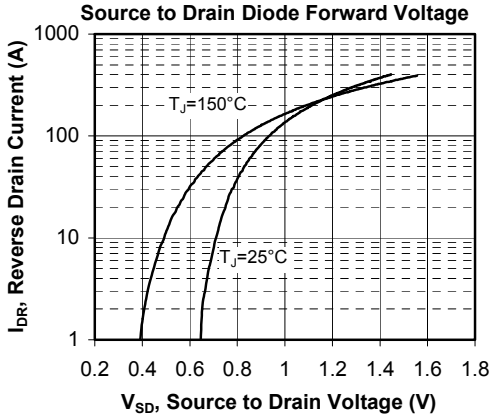

Delay Times vs Current
td(off)
td(on)
VDS=333V
RG=2Ω
TJ=125°C
L=100µH
td(on) and td(off) (ns)
ID, Drain Current (A)


Rise and Fall times vs Current
VDS=333V
RG=2Ω
TJ=125°C
L=100µH
tf
tr
tr and tf (ns)
ID, Drain Current (A)


Switching Energy vs Current
VDS=333V
RG=2Ω
TJ=125°C
L=100µH
Eon
Eoff
Switching Energy (mJ)
ID, Drain Current (A)


Switching Energy vs Gate Resistance
VDS=333V
ID=90A
TJ=125°C
L=100µH
Eoff
Eon
Eoff
Switching Energy (mJ)
Gate Resistance (Ohms)


Operating Frequency vs Drain Current
ZVS
VDS=333V
D=50%
RG=2Ω
TJ=125°C
TC=75°C
ZCS
Hard
switching
Frequency (kHz)
ID, Drain Current (A)


Source to Drain Diode Forward Voltage
TJ=150°C
TJ=25°C
IDR, Reverse Drain Current (A)
VSD, Source to Drain Voltage (V)

DISCLAIMER

The information contained in the document (unless it is publicly available on the Web without access restrictions) is PROPRIETARY AND CONFIDENTIAL information of Microsemi and cannot be copied, published, uploaded, posted, transmitted, distributed or disclosed or used without the express duly signed written consent of Microsemi. If the recipient of this document has entered into a disclosure agreement with Microsemi, then the terms of such Agreement will also apply. This document and the information contained herein may not be modified, by any person other than authorized personnel of Microsemi. No license under any patent, copyright, trade secret or other intellectual property right is granted to or conferred upon you by disclosure or delivery of the information, either expressly, by implication, inducement, estoppels or otherwise. Any license under such intellectual property rights must be approved by Microsemi in writing signed by an officer of Microsemi.

Microsemi reserves the right to change the configuration, functionality and performance of its products at anytime without any notice. This product has been subject to limited testing and should not be used in conjunction with life-support or other mission-critical equipment or applications. Microsemi assumes no liability whatsoever, and Microsemi disclaims any express or implied warranty, relating to sale and/or use of Microsemi products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Any performance specifications believed to be reliable but are not verified and customer or user must conduct and complete all performance and other testing of this product as well as any user or customers final application. User or customer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the customer's and user's responsibility to independently determine suitability of any Microsemi product and to test and verify the same. The information contained herein is provided "AS IS, WHERE IS" and with all faults, and the entire risk associated with such information is entirely with the User. Microsemi specifically disclaims any liability of any kind including for consequential, incidental and punitive damages as well as lost profit. The product is subject to other terms and conditions which can be located on the web at http://www.microsemi.com/legal/tnc.asp

Life Support Application

Seller's Products are not designed, intended, or authorized for use as components in systems intended for space, aviation, surgical implant into the body, in other applications intended to support or sustain life, or for any other application in which the failure of the Seller's Product could create a situation where personal injury, death or property damage or loss may occur (collectively "Life Support Applications").

Buyer agrees not to use Products in any Life Support Applications and to the extent it does it shall conduct extensive testing of the Product in such applications and further agrees to indemnify and hold Seller, and its officers, employees, subsidiaries, affiliates, agents, sales representatives and distributors harmless against all claims, costs, damages and expenses, and attorneys' fees and costs arising, directly or directly, out of any claims of personal injury, death, damage or otherwise associated with the use of the goods in Life Support Applications, even if such claim includes allegations that Seller was negligent regarding the design or manufacture of the goods.

Buyer must notify Seller in writing before using Seller's Products in Life Support Applications. Seller will study with Buyer alternative solutions to meet Buyer application specification based on Sellers sales conditions applicable for the new proposed specific part.